



Docket No.: 43890-439

PATENT

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re Application of

Noboru MOHRI, et al.

Serial No.:

(Divisional of Serial No. 09/041,666)

Filed: September 14, 2000

For: PACKAGING SUBSTRATE AND METHOD OF MANUFACTURING THE SAME

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Group Art Unit:

Examiner:

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**PRELIMINARY AMENDMENT**

Assistant Commissioner for Patents  
Washington, DC 20231

Sir:

Prior to examination of the above-referenced application, please amend the application as follows:

**IN THE SPECIFICATION:**

Page 26, line 14, after " $7.2 \times 10^{-6}/C.$ ", please insert --It is noted that the first insulating layer 6 and the second insulating layer 16 have a thermal expansion coefficient +/- 10% of the thermal expansion coefficient of the circuit substrate. In addition, the first insulating layer 6 and the second insulating layer 16 can be formed simultaneously.--

**IN THE CLAIMS:**

Please amend claim 22 as follows:

22. (Amended) A packaging substrate comprising:

a circuit substrate,

a first conductor pattern formed by an intaglio printing means based on flexible resin base

material and transferred onto said circuit substrate,

a second conductor pattern electrically connected to said first conductor pattern on the opposite side of the circuit substrate via through holes, and

a first ball-shaped solder joined to said second conductor pattern,

wherein a surface roughness of the circuit substrate is made larger on a printing surface of the second conductor pattern than on a printing surface of the first conductor pattern.

#### REMARKS

Entry of this preliminary amendment is respectfully requested.

Respectfully submitted,

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